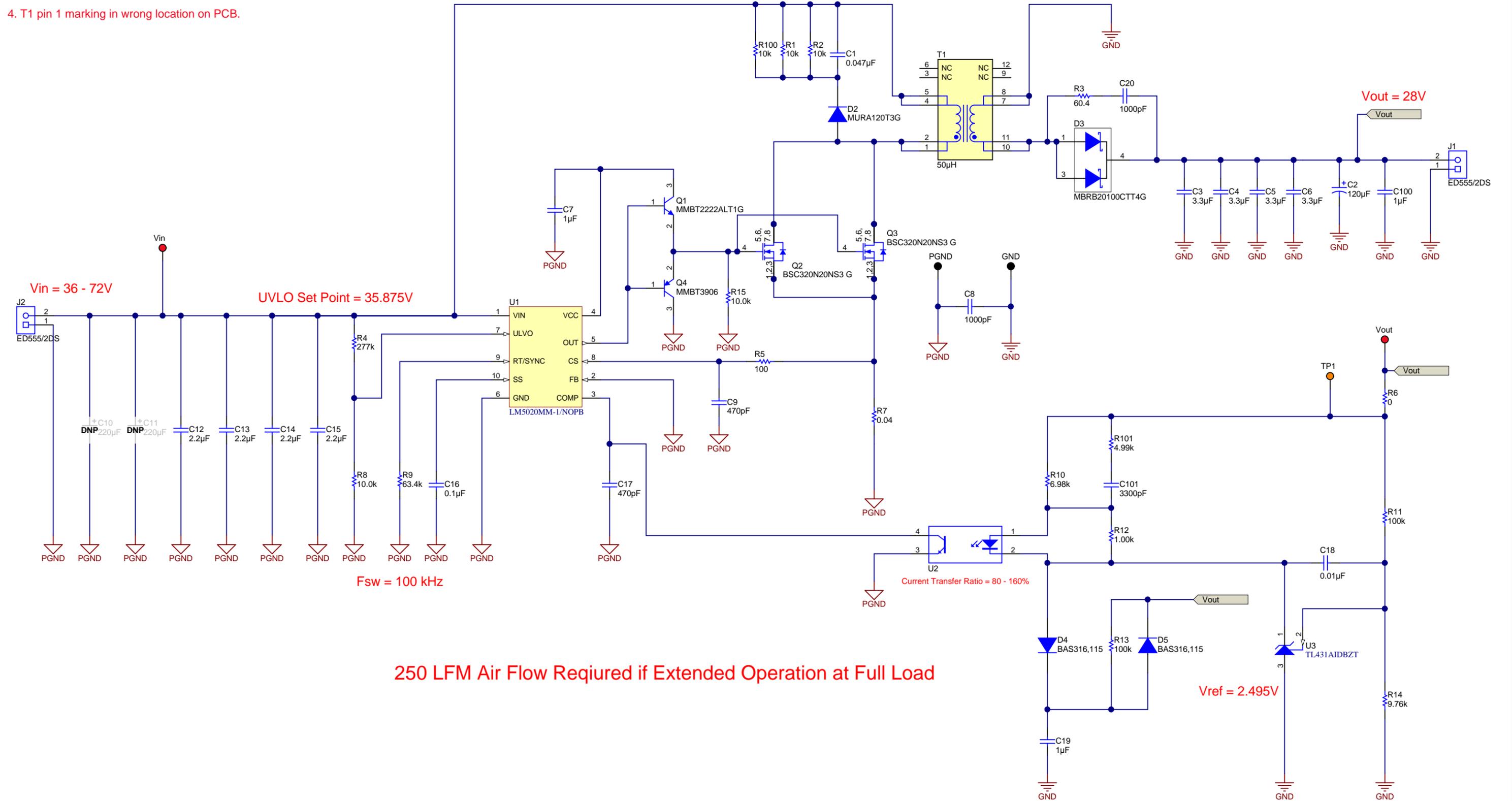


**Assembly Notes:**

1. Built on PMP20777PCB Rev A.
2. C100, C101, R100 and R101 were added for Rev B.
3. L1 was removed and shorted.
4. T1 pin 1 marking in wrong location on PCB.



250 LFM Air Flow Required if Extended Operation at Full Load

Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 5/2/2017
TID #: N/A	Project Title: 36-72Vin, 28V/3A Supply	
Number: PMP20777	Rev: B	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: PMP20777B_SCH.SchDoc	Size: B
Engineer: Ben Lough	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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